NTLUS3A40PZ

MOSFET – Power, Single, P-Channel, ESD, μCool, UDFN, 2.0x2.0x0.55 mm
-20 V, -9.4 A

ON Semiconductor®

http://onsemi.com

Features

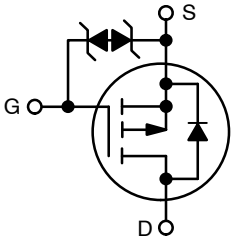
- UDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile UDFN 2.0x2.0x0.55 mm for Board Space Saving
- Lowest RDS(on) in 2.0x2.0 Package
- ESD Protected
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- High Side Load Switch
- PA Switch and Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Cell Phones, PMP, DSC, GPS, and others

MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX
−20 V	29 mΩ @ −4.5 V	−9.4 A
	39 mΩ @ −2.5 V	
	60 mΩ @ −1.8 V	
	120 mΩ @ −1.5 V	



P−Channel MOSFET

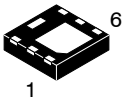
MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Units
Drain-to-Source Voltage			V_{DSS}	−20	V
Gate-to-Source Voltage			V_{GS}	±8.0	V
Continuous Drain Current (Note 1)	Steady State	T_A = 25°C	I_D	−6.4	A
		T_A = 85°C		−4.6	
	t ≤ 5 s	T_A = 25°C		−9.4	
Power Dissipation (Note 1)	Steady State	T_A = 25°C	P_D	1.7	W
	t ≤ 5 s	T_A = 25°C		3.8	
Continuous Drain Current (Note 2)	Steady State	T_A = 25°C	I_D	−4.0	A
		T_A = 85°C		−2.9	
Power Dissipation (Note 2)		T_A = 25°C	P_D	0.7	W
Pulsed Drain Current		tp = 10 μs	I_{DM}	−30	A
Operating Junction and Storage Temperature			T_J, T_{STG}	-55 to 150	°C
Source Current (Body Diode) (Note 2)			I_S	−1.0	A
Lead Temperature for Soldering Purposes (1/8″ from case for 10 s)			T_L	260	°C
ESD Rating (HBM) per JESD22−A114F			ESD	>2000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

MARKING DIAGRAM

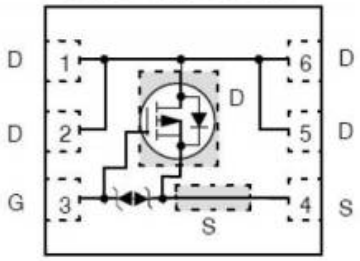


UDFN6
CASE 517BG
μCOOL™

AA = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

2. Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm^2, 2 oz. Cu.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Units
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	72	°C/W
Junction-to-Ambient – t ≤ 5 s (Note 3)	$R_{\theta JA}$	33	
Junction-to-Ambient – Steady State min Pad (Note 4)	$R_{\theta JA}$	189	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Units
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = −250 μA		−20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	I_D = −250 μA, ref to 25°C			−5.0		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = −20 V	T_J = 25°C			−1.0	μA
			T_J = 85°C			−10	
Gate-to-Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±8.0 V				±10	μA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = −250 μA		−0.4		−1.0	V
Negative Threshold Temp. Coefficient	$V_{GS(TH)}/T_J$				3.0		mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	V_{GS} = −4.5 V, I_D = −6.4 A			23	29	mΩ
		V_{GS} = −2.5 V, I_D = −4.8 A			31	39	
		V_{GS} = −1.8 V, I_D = −2.5 A			43	60	
		V_{GS} = −1.5 V, I_D = −1.5 A			60	120	
Forward Transconductance	g_{FS}	V_{DS} = −15 V, I_D = −4.0 A			18		S
CHARGES, CAPACITANCES & GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = −15 V			2600		pF
Output Capacitance	C_{OSS}				200		
Reverse Transfer Capacitance	C_{RSS}				190		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = −4.5 V, V_{DS} = −15 V; I_D = −4.0 A			29		nC
Threshold Gate Charge	$Q_{G(TH)}$				1.4		
Gate-to-Source Charge	Q_{GS}				3.7		
Gate-to-Drain Charge	Q_{GD}				8.1		
SWITCHING CHARACTERISTICS, VGS = 4.5 V (Note 6)							
Turn-On Delay Time	$t_{d(ON)}$	V_{GS} = −4.5 V, V_{DD} = −15 V, I_D = −4.0 A, R_G = 1 Ω			9.0		ns
Rise Time	t_r				18		
Turn-Off Delay Time	$t_{d(OFF)}$				126		
Fall Time	t_f				71		
DRAIN-SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	VSD	V_{GS} = 0 V, I_S = −1.0 A	T_J = 25°C		0.65	1.0	V
			T_J = 125°C		0.55		

3. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
4. Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm^2, 2 oz. Cu.
5. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS						
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, dis/dt = 100 A/μs, I_S = −1.0 A		25		ns
Charge Time	t_a			10		
Discharge Time	t_b			15		
Reverse Recovery Charge	Q_{RR}			13.6		nC

3. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
4. Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm^2, 2 oz. Cu.
5. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

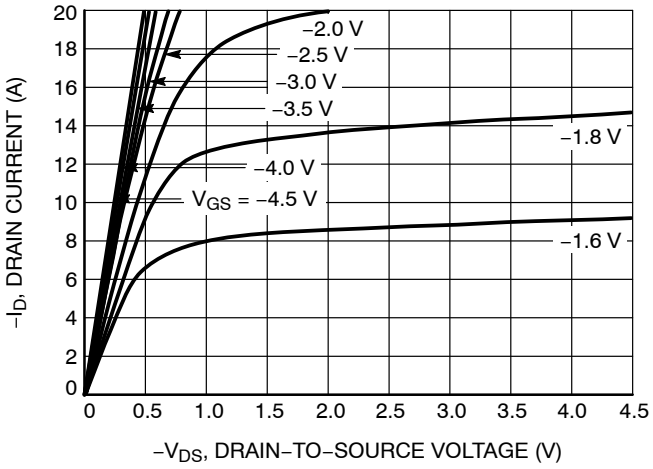


Figure 1. On−Region Characteristics

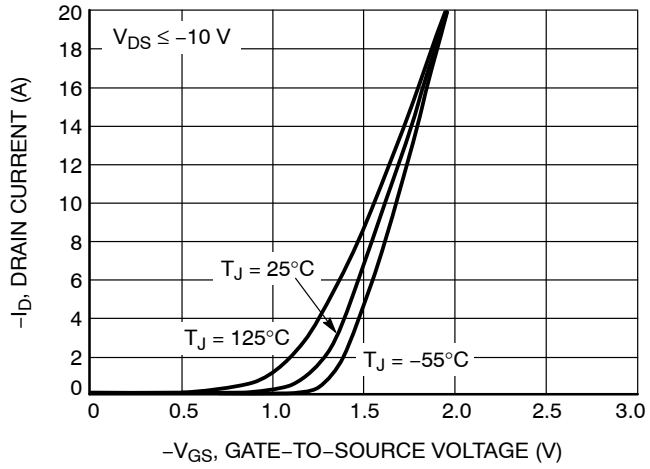


Figure 2. Transfer Characteristics

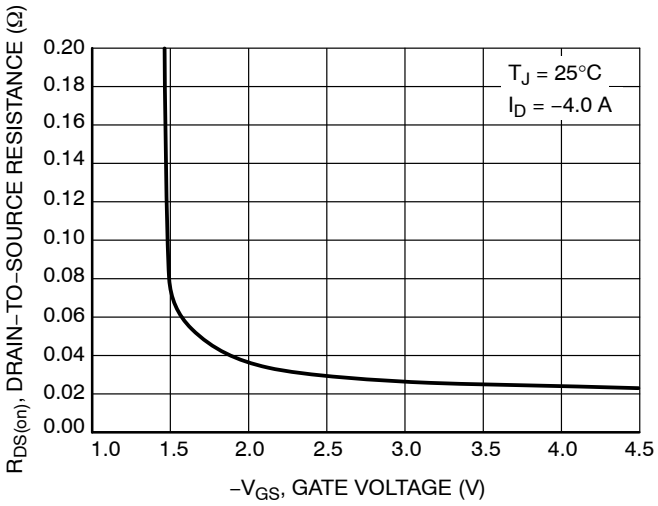


Figure 3. On−Resistance vs. Gate−to−Source Voltage

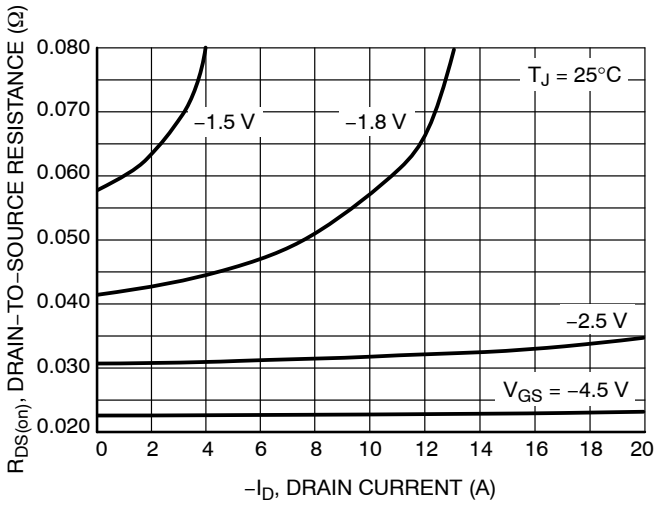


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

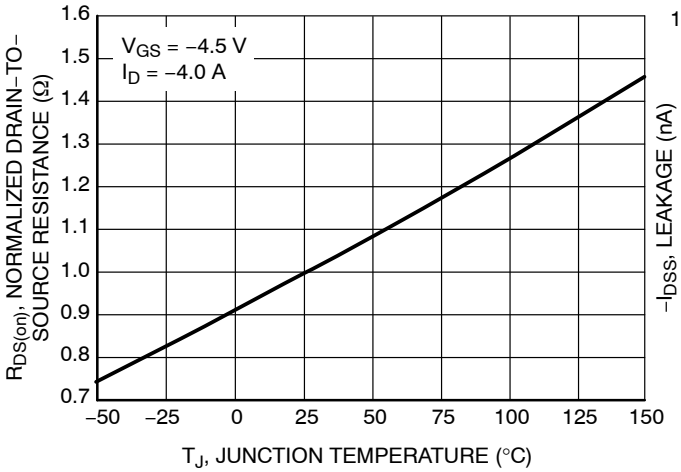


Figure 5. On−Resistance Variation with Temperature

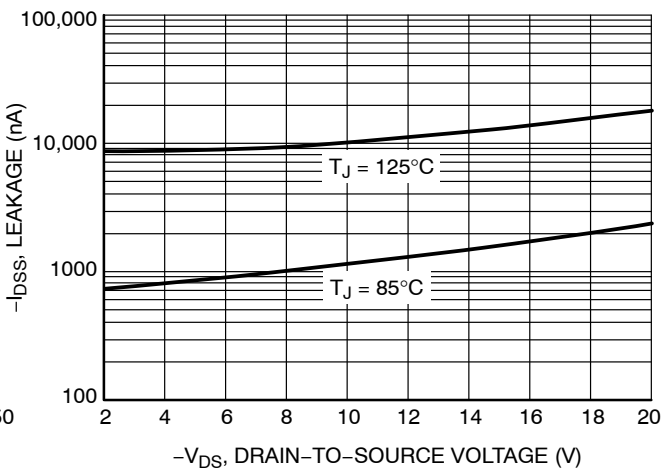


Figure 6. Drain−to−Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

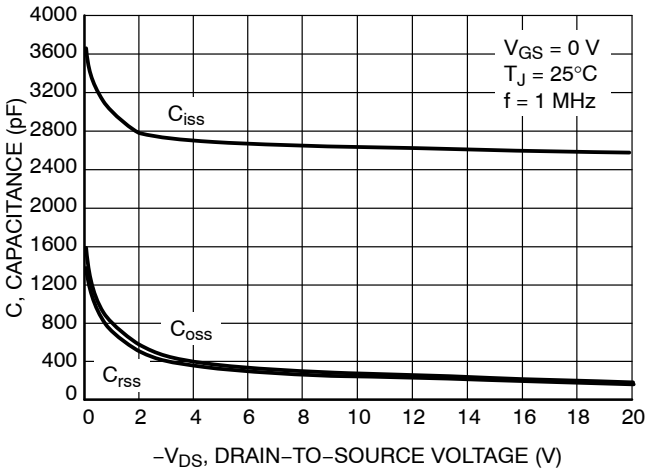


Figure 7. Capacitance Variation

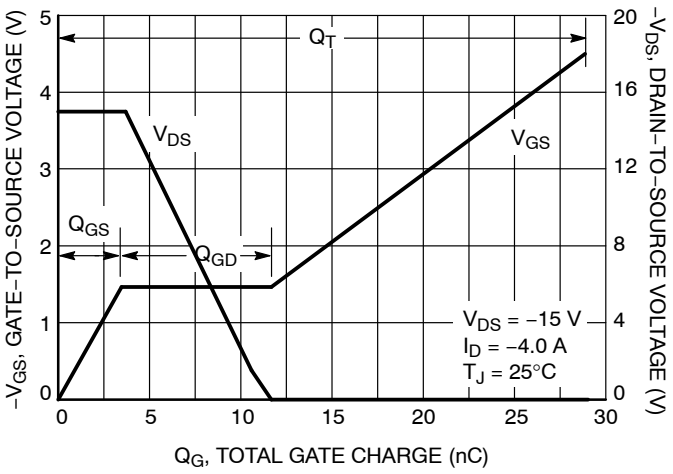


Figure 8. Gate−to−Source and Drain−to−Source Voltage vs. Total Charge

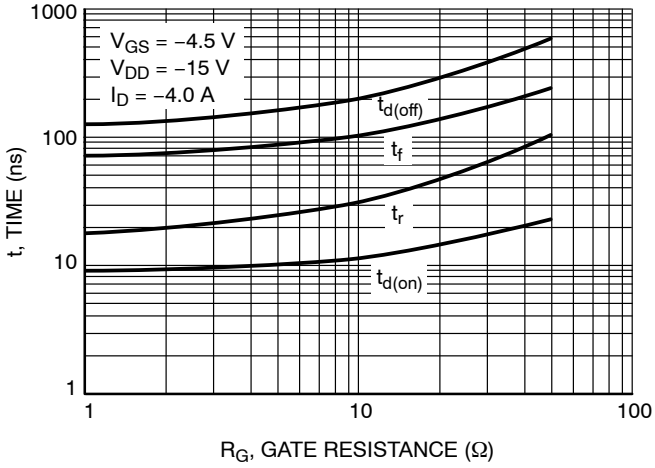


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

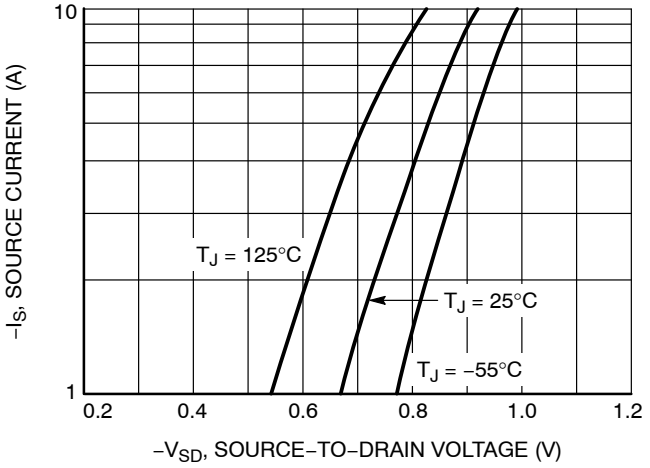


Figure 10. Diode Forward Voltage vs. Current

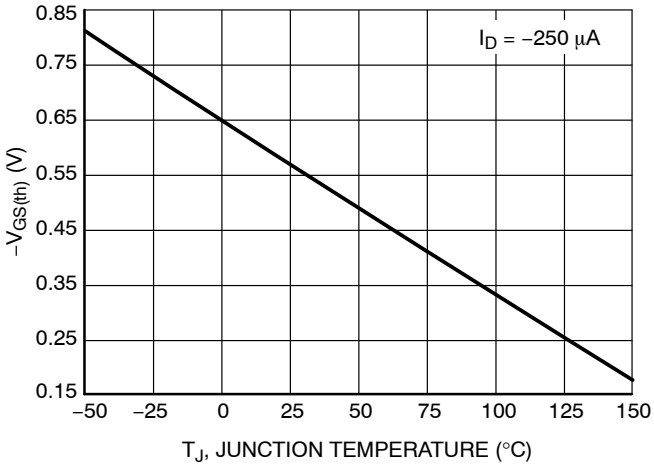


Figure 11. Threshold Voltage

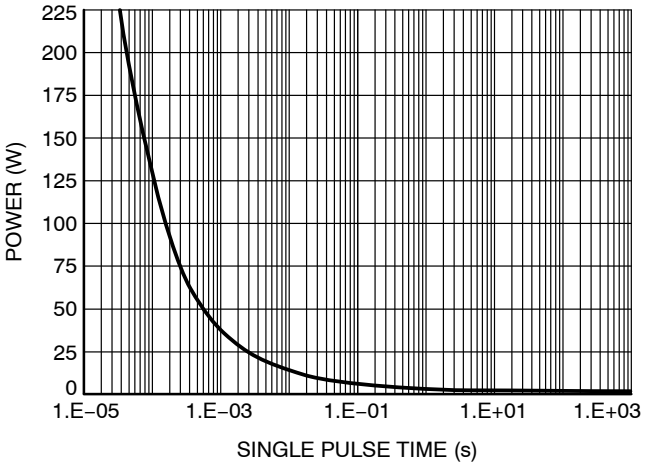


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS

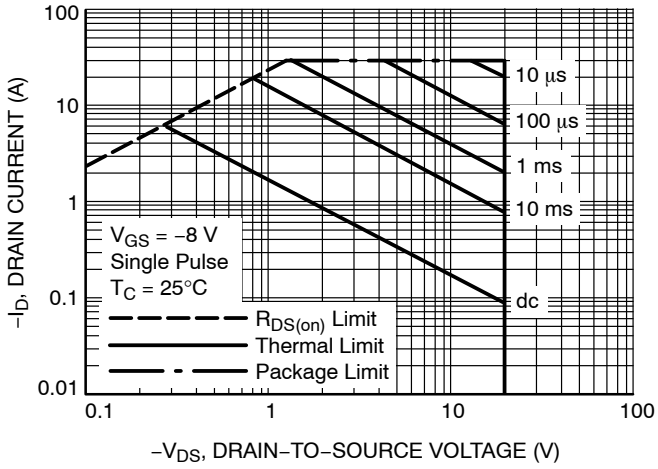


Figure 13. Maximum Rated Forward Biased Safe Operating Area

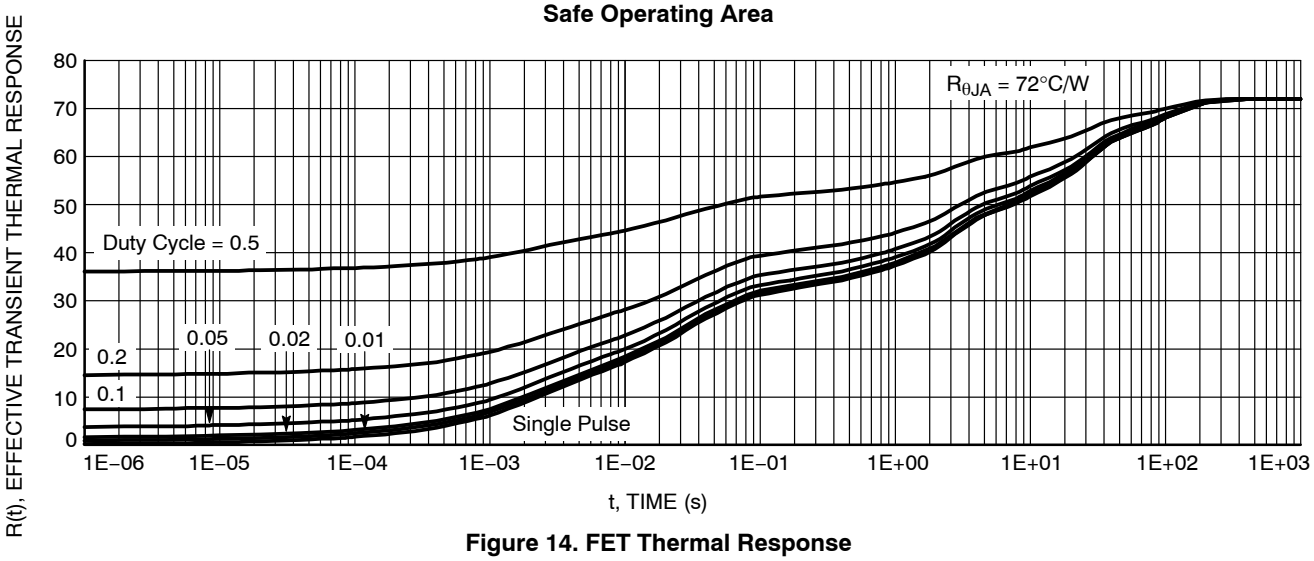


Figure 14. FET Thermal Response

DEVICE ORDERING INFORMATION

Device	Package	Shipping†
NTLUS3A40PZTAG	UDFN6 (Pb−Free)	3000 / Tape & Reel
NTLUS3A40PZTBG	UDFN6 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

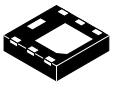
μCool is a trademark of Semiconductor Components Industries, LLC (SCILLC).

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

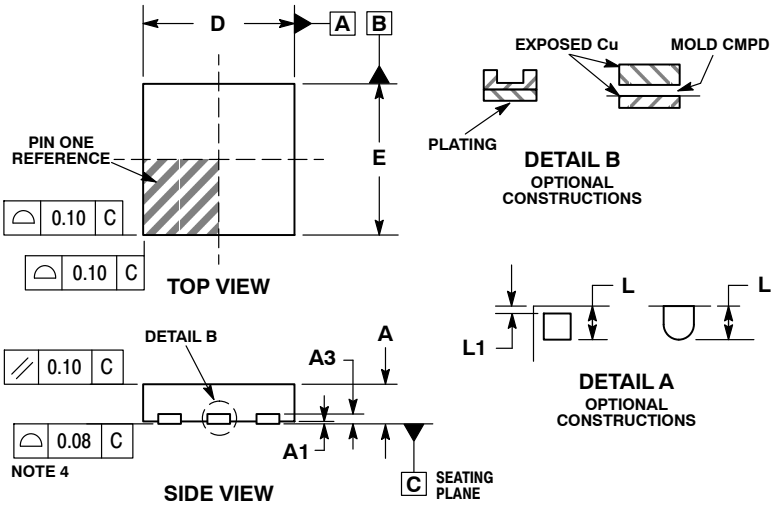
ON Semiconductor®

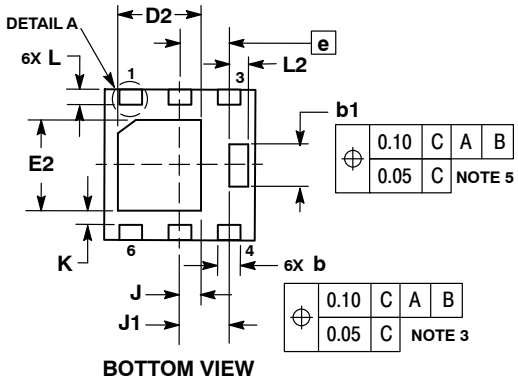
UDFN6 2x2, 0.65P
CASE 517BG−01
ISSUE A

DATE 04 FEB 2010



SCALE 4:1

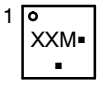




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
1. CENTER TERMINAL LEAD IS OPTIONAL. CENTER TERMINAL IS CONNECTED TO TERMINAL LEAD # 4.
2. LEADS 1, 2, 5 AND 6 ARE TIED TO THE FLAG.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.25	0.35
b1	0.51	0.61
D	2.00 BSC	
D2	1.00	1.20
E	2.00 BSC	
E2	1.10	1.30
e	0.65 BSC	
K	0.15 REF	
J	0.27 BSC	
J1	0.65 BSC	
L	0.20	0.30
L1	---	0.10
L2	0.20	0.30

GENERIC MARKING DIAGRAM*

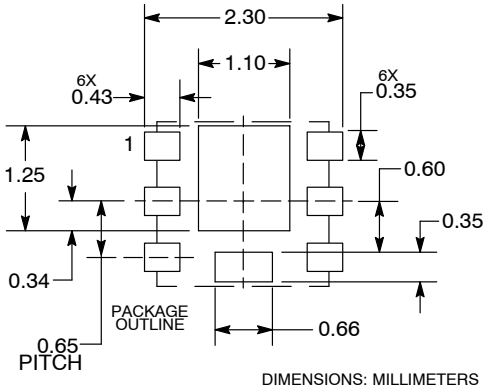


XX = Specific Device Code
M = Date Code

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

DOCUMENT NUMBER:	**98AON48158E**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**UDFN6 2X2, 0.65P**		**PAGE 1 OF 1**

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

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